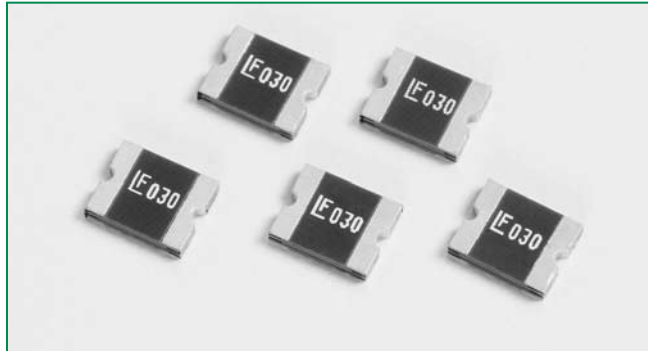




Description

The 2016L series device provides surface mount overcurrent protection for low voltage ($\leq 60V$) applications where resettable protection is desired.

Features

- RoHS compliant and lead-free
- Fast response to fault currents
- High voltage
- Low-profile

Applications

- IEE1394 port protection
- Powered ethernet port protection (IEEE 802.3 af)
- Automotive electronic control module protection
- Low voltage telecom equipment protection

Agency Approvals

AGENCY	AGENCY FILE NUMBER
	E183209
	R50082521

Electrical Characteristics

Part Number	Marking	I_{hold} (A)	I_{trip} (A)	V_{max} (Vdc)	I_{max} (A)	P_d max. (W)	Maximum Time To Trip		Resistance			Agency Approvals	
							Current (A)	Time (Sec.)	R_{min} (Ω)	R_{typ} (Ω)	R_{1max} (Ω)		
2016L030	LF030	0.30	0.60	60	20	1.40	1.50	3.00	0.500	1.400	2.300	X	X
2016L050	LF050	0.55	1.10	60	20	1.40	2.50	5.00	0.200	0.700	1.000	X	X
2016L100	LF100	1.10	2.20	15	40	1.40	8.00	0.50	0.100	0.250	0.400	X	X
2016L100/33	LF100-33	1.10	2.20	33	40	1.40	8.00	0.50	0.100	0.250	0.400	X	X
2016L150	LF150	1.50	3.00	15	40	1.40	8.00	1.00	0.070	0.130	0.180	X	X
2016L200	LF200	2.00	4.20	6	40	1.40	8.00	3.00	0.048	0.070	0.100	X	X

I_{hold} = Hold current: maximum current device will pass without tripping in 20°C still air.

I_{trip} = Trip current: minimum current at which the device will trip in 20°C still air.

V_{max} = Maximum voltage device can withstand without damage at rated current (I_{max})

I_{max} = Maximum fault current device can withstand without damage at rated voltage (V_{max})

P_d = Power dissipated from device when in the tripped state at 20°C still air.

R_{min} = Minimum resistance of device in initial (un-soldered) state.

R_{typ} = Typical resistance of device in initial (un-soldered) state.

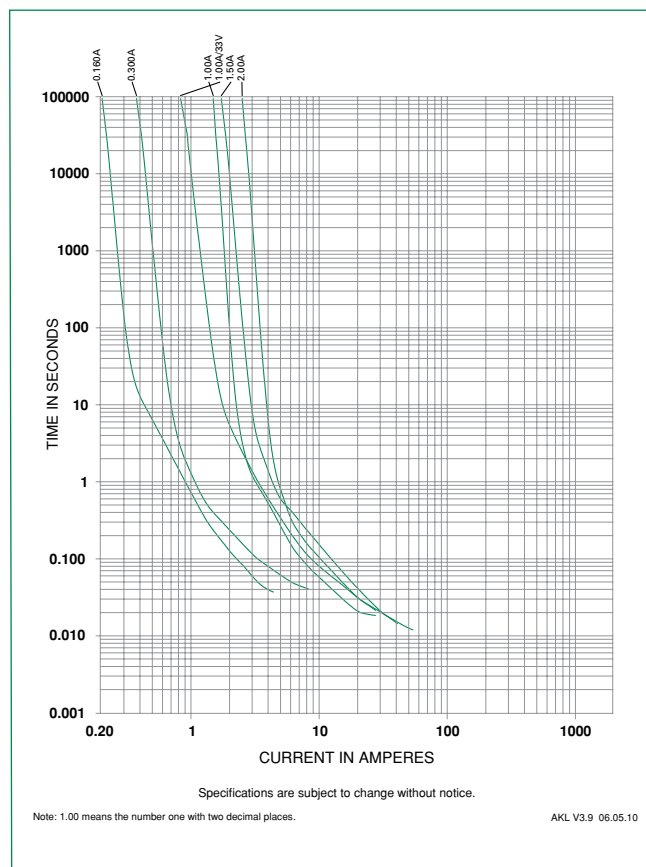
R_{1max} = Maximum resistance of device at 20°C measured one hour after tripping or reflow soldering of 260°C for 20 sec.

Caution: Operation beyond the specified rating may result in damage and possible arcing and flame.

Temperature Derating

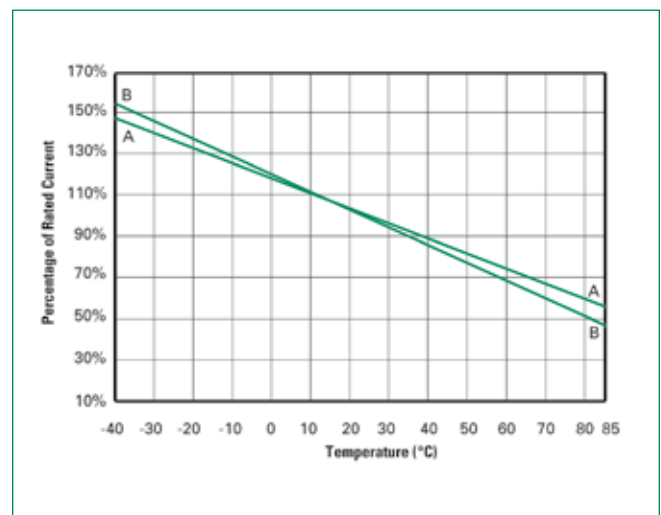
	Ambient Operation Temperature								
	-40°C	-20°C	0°C	23°C	40°C	50°C	60°C	70°C	85°C
Part Number	Hold Current (A)								
2016L030	0.45	0.40	0.35	0.30	0.25	0.23	0.20	0.18	0.14
2016L050	0.93	0.80	0.65	0.50	0.38	0.32	0.25	0.19	0.09
2016L100	1.66	1.47	1.29	1.10	0.91	0.83	0.73	0.64	0.50
2016L100/33	1.66	1.47	1.29	1.10	0.91	0.83	0.73	0.64	0.50
2016L150	2.26	2.00	1.76	1.50	1.24	1.13	1.00	0.87	0.68
2016L200	2.80	2.50	2.19	2.00	1.84	1.74	1.50	1.34	1.14

Average Time Current Curves



The average time current curves and temperature derating curve performance is affected by a number of variables, and these curves provided as guidance only. Customer must verify the performance in their application.

Temperature Derating Curve



A: 2016L050
 2016L100
 2016L200

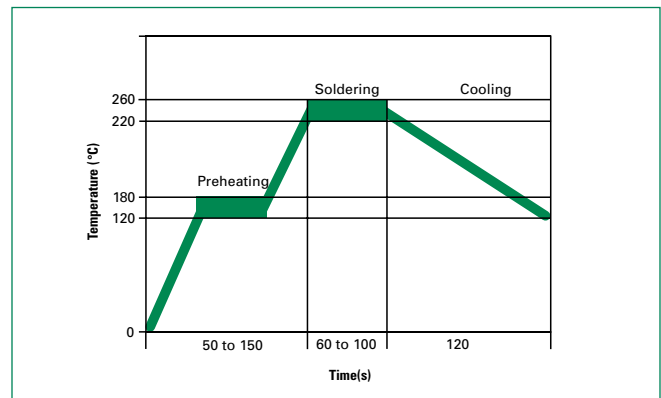
B: 2016L030
 2016L100/33
 2016L150

Soldering Parameters

Condition	Reflow
Peak Temp/ Duration Time	260°C / 10 Sec
Time above liquids (TAL) 220°C	60 Sec ~ 100 Sec
Preheat 120°C~ 180°C	50 Sec ~ 150 Sec
Storage Condition	0°C~35°C, ≤70%RH

- Recommended reflow methods: IR, vapor phase oven, hot air oven, N₂ environment for lead-free
- Devices are not designed to be wave soldered to the bottom side of the board.
- Recommended maximum paste thickness is 0.25mm (0.010 inch)
- Devices can be cleaned using standard industry methods and solvents.

Note: If reflow temperatures exceed the recommended profile, devices may not meet the performance requirements.



Physical Specifications

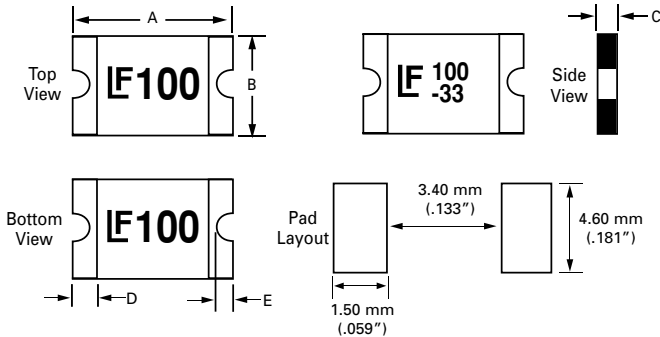
Terminal Material	Solder-Plated Copper (Solder Material: Matte Tin(Sn))
Lead Solderability	Meets EIA Specification RS186-9E, ANSI/J-STD-002 Category 3.

Environmental Specifications

Operating/Storage Temperature	-40°C to +85°C
Maximum Device Surface Temperature in Tripped State	125°C
Passive Aging	+85°C, 1000 hours ±5% typical resistance change
Humidity Aging	+85°C, 85%R.H. 1000 hours ±5% typical resistance change
Thermal Shock	MIL-STD-202 Method 107G +85°C/-40°C 20 times -30% typical resistance change
Solvent Resistance	MIL-STD-202, Method 215 No change
Vibration	MIL-STD-883C, Method 2007.1, Condition A No change

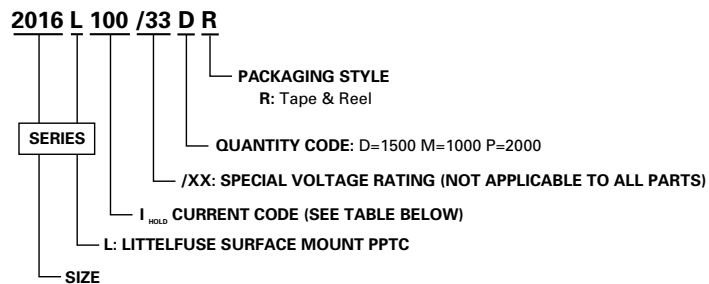
Dimensions (mm)

MARKING CODE VARIES
 WITH AMPERAGE AND VOLTAGE RATING
 (SEE CHART)
 SHOWN ARE:
 - 1.0A/15V RATING (LEFT)
 - 1.0A/33V RATING (RIGHT)



Part Number	A				B				C				D		E			
	Inches		mm		Inches		mm		Inches		mm		Inches	mm	Inches	mm	Inches	mm
	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Min.	Min.	Max.	Min.	Max.
2016L030	0.19	0.21	4.72	5.44	0.15	0.17	3.7	4.43	0.03	0.05	0.75	1.25	0.01	0.03	0.01	0.03	0.25	0.65
2016L050	0.19	0.21	4.72	5.44	0.15	0.17	3.7	4.43	0.05	0.08	1.2	2	0.01	0.03	0.01	0.03	0.25	0.65
2016L100	0.19	0.21	4.72	5.44	0.15	0.17	3.7	4.43	0.02	0.03	0.5	0.75	0.01	0.03	0.01	0.03	0.25	0.65
2016L100/33	0.19	0.21	4.72	5.44	0.15	0.17	3.7	4.43	0.03	0.05	0.75	1.25	0.01	0.03	0.01	0.03	0.25	0.65
2016L150	0.19	0.21	4.72	5.44	0.15	0.17	3.7	4.43	0.03	0.06	0.75	1.55	0.01	0.03	0.01	0.03	0.25	0.65
2016L200	0.19	0.21	4.72	5.44	0.15	0.17	3.7	4.43	0.02	0.03	0.5	0.75	0.01	0.03	0.01	0.03	0.25	0.65

Part Numbering System



Packaging

I_{hold} (A)	I_{hold} Code	Voltage Option	Packaging Option	Quantity	Quantity & Packaging Codes
0.30	030		Tape and Reel	1500	DR
0.55	050		Tape and Reel	1000	MR
1.10	100		Tape and Reel	2000	PR
		/33	Tape and Reel	1500	DR
1.50	150		Tape and Reel	1500	DR
2.00	200		Tape and Reel	2000	PR